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ABSTRACT OF THE DISCLOSURE

An abrasive slurry contains an alumina grain, an inorganic salt, a water-soluble chelating agent, an abrasive oil and a hardly water-soluble chelate aluminum salt or chelate nickel salt. The alumina grain has an average particle diameter of from 0.05 to 1 μm in an amount of from 0.1 to 10% by weight. The inorganic salt is selected from the group consisting of water-soluble inorganic aluminum salt and nickel salt in an amount of from 0.1 to 3% by weight. The content of the water-soluble chelating agent is from 0.1 to 3% by weight. The content of the abrasive oil is from 0.1 to 10% by weight. The content of the hardly water-soluble chelate aluminum salt or chelate nickel salt is not more than 0.1% by weight. The abrasive slurry is used for abrading an insulation layer of a semiconductor integrated circuit and a magnetic thin film head while they are produced.

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